

Electronic Patent Application Fee Transmittal

Application Number:	10717122			
Filing Date:	19-Nov-2003			
Title of Invention:	Dielectric barrier layer for a copper metallization layer having a varying silicon concentration along its thickness			
First Named Inventor/Applicant Name:	Larry Zhao			
Filer:	J. Mike Amerson/Mary Paul			
Attorney Docket Number:	2000.106900			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1020	1020

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1020